

QF2055
No Clean Halogen-Free Liquid Flux

Product Description

QF2055 is a no clean, halogen-free RMA flux. It is specially designed to deliver the best of solderability and minimize micro-solderballs for conventional and circuit board assemblies. This no-clean and clear residue flux shows superior wetting on difficult-to-solder substrates. It is compatible with lead free applications.

Application

QF2055 is specially formulated for spraying, foaming as well as dipping (Cu substrate) processes. Recommended onboard preheat is 80–120°C and under-board preheat temperature is 90–140°C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Thinning of flux is necessary if it is detected to have high specific gravity during the production. Asahi's complementary Solvent #2000 is recommended. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, QF2055 can be stored for up to 6 months. QF2055 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

DISCLAIMER OF LIABILITY

"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."

Specification (Preliminary)

Item	Result
State	Liquid
Colour	Pale yellow
Specific Gravity @ 25°C	0.797 ± 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content	
IPC-TM-650 2.3.34	5.3 ± 0.2 wt%
JIS Z 3197 8.1.3	
Halide Content	Not detected
JIS Z 3197 8.1.4.2.1	
Halogen Content	Not detected
BS EN 14582	
Acid Value Test	27.5 ± 2 mg KOH/ g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance	> 1 x 10 ⁸ Ω, Pass
(85°C, 85%RH, 168hrs)	
IPC-TM-650 2.6.3.3	
Electromigration	Pass
(85°C, 88.5%RH, 596hrs)	
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "L", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	RELO
IPC J-STD-004	
Spread Factor	> 65% (SCS7)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Shiny

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